

02-11-2009

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PATENTS ON



103547639

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1-30-09

1. Name of conveying party(ies)/Execution Date(s):

MAKOTO TSUKAMOTO (01/05/2009), JUN
HIRAI (01/05/2009), AYATAKA NISHIO
(01/06/2009), AND NAOMASA TAKAHASHI
(01/07/2009)

Execution Date(s): In parentheses after inventor name

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of Conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other _____

2. Name and address of receiving party(ies)

Name: SONY CORPORATION

Internal Address: _____

Street Address: _____

1-7-1 Konan, Minato-ku
Tokyo 108-0075
JAPAN

City: _____

State: _____

Country: _____

Zip: _____

Additional name(s) & address(es) attached: Yes No

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Dennis M. Smid, Esq.
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6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____

Expiration Date _____

b. Deposit Account Number 12-1095

Authorized User Name Dennis M. Smid, Esq.

9. Signature:

Signature

Dennis M. Smid, Esq. - 34,930

Name of Person Signing

02/10/2009 DBYRNE 0000022 121095 1232229

01 FC:8021

February 30, 2009

Date

Total number of pages including cover sheet, attachments, and documents:

3

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in GRADATION CONVERTING DEVICE, GRADATION CONVERTING METHOD, AND COMPUTER PROGRAM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all prior rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue to said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require or prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known or accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date in this application in the spaces that follow: Serial Number: _____, Filing Date: _____

This assignment executed on the dates indicated below.

Makoto TSUKAMOTO	January 5, 2009
Name of first or sole inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of first or sole inventor	
Makoto Tsukamoto	January 5, 2009
Signature of first or sole inventor	Date of this assignment

Jun HIRAI
 Name of second inventor
 Tokyo, Japan
 Residence of second inventor
 Jun Hirai
 Signature of second inventor
 January 5, 2009
 Execution date of U.S. Patent Application
 Date of this assignment

Ayataka NISHIO
 Name of third inventor
 Kanagawa, Japan
 Residence of third inventor
 Ayataka Nishio
 Signature of third inventor
 January 6, 2009
 Execution date of U.S. Patent Application
 Date of this assignment

Naomasa TAKAHASHI
 Name of fourth inventor
 Chiba, Japan
 Residence of fourth inventor
 Naomasa Takahashi
 Signature of fourth inventor
 January 7, 2009
 Execution date of U.S. Patent Application
 Date of this assignment

Name of fifth inventor
 Residence of fifth inventor
 Signature of fifth inventor
 Execution date of U.S. Patent Application
 Date of this assignment